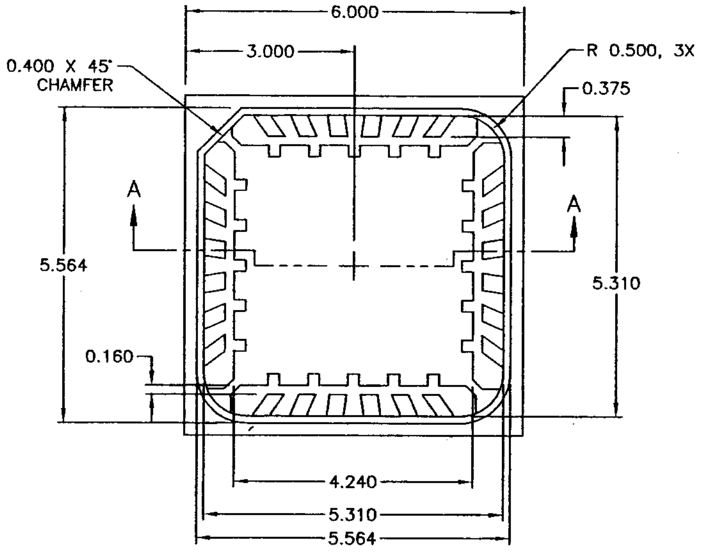
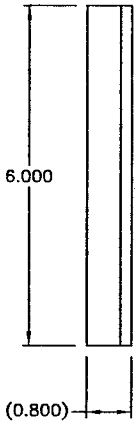
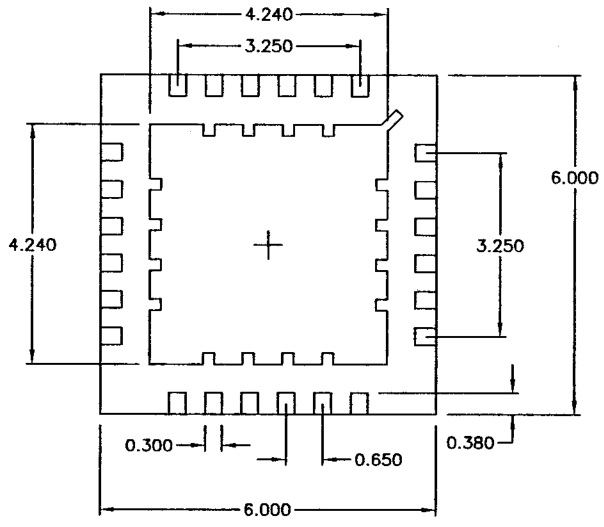
SSM P/N: QFN02402

SEMPAK REVISIONS			
ECN NO.	DATE	DESCRIPTION	APPROVED

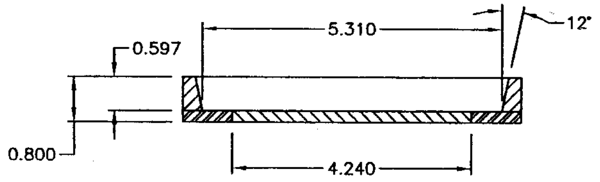


TOP VIEW





BOTTOM VIEW



SECTION A-A

NOTES:
1. BODY: PLASTIC, SEMICONDUCTOR GRADE.
3. LEAD FRAME: COPPER, 194 FH.
4. LEAD FINISH: FULL GOLD PLATE.
5. FRAME THICKNESS: 0.2030 ±.0076.
6. DIE PAD: 4.240mm X 4.240mm.
7. JEDEC OUTLINE: MO-220 (VJJC-1).

THIRD ANGLE PROJECTION	DRAWN BY	DATE 10/20/06	24 LEAD 6mm X 6mm
UNLESS OTHERWISE SPECIFIED DIMENSIONS ARE IN **MILLIMETERS** TOLERANCES ARE: X.XX ± 0.015 X.XXXX ±--- X.XXX ± 0.050 ANGLES: ± 1°	APP BY	DATE 10/20/06	
	CUSTOMER ---		QFN6X6-024 REV 2
DO NOT SCALE DRAWING			

SPECTRUM
SEMICONDUCTOR MATERIALS, INC.

www.spectrum-semi.com Phone: 408-435-5555 Fax: 408-435-8226